

Title (en)  
CONTROLLABLY DEGRADABLE COMPOSITION OF HETEROATOM CARBOCYCLIC OR EPOXY RESIN AND CURING AGENT

Title (de)  
KONTROLLIERT ABBAUBARE ZUSAMMENSETZUNG BASIEREND AUF EINEM HETEROATOM-CARBONSÄURE- ODER EPOXY-HARZ UND EINEM HÄRTUNGSMITTEL

Title (fr)  
COMPOSITION DONT LA DEGRADATION EST REGULABLE, A BASE DE RESINE EPOXY OU CARBOCYCLIQUE D'HETEROATOME ET A BASE D'UN AGENT DE DURCISSEMENT

Publication  
**EP 1194953 A1 20020410 (EN)**

Application  
**EP 00942630 A 20000616**

Priority

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- US 13948699 P 19990617
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- US 19339100 P 20000331
- US 21047000 P 20000609

Abstract (en)  
[origin: WO0079582A1] A reworkable underfilling sealing material (33) for the attachment of a semiconductor device (32) to a carrier substrate (31) is prepared from a composition comprising a curable resin (a) which is a resin with a (thio)ether or carbonate core structure and a heteroatom-containing carbocyclic structure, an epoxy resin having at least one alkylene oxide residue, or an epoxy resin with a monoxide (thio)ester or carbonate coreactant diluent; and (b) a curing agent including a polyamine, an epoxy- or novolac-modified amine, an amide compound or an imidazole; optionally with an anhydride.

IPC 1-7  
**H01L 21/56**; **H01L 21/58**; **C08K 3/36**; **C08L 63/00**; **C08L 69/00**; **C08L 71/00**

IPC 8 full level  
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